ABSTRACT OF THE DISCLOSURE

A thermally-conductive epoxy resin molded article conducting heat generated from electronic components and the like, and a method of manufacturing the same are disclosed. The thermally-conductive epoxy resin molded article according to the present invention is obtained by curing an epoxy resin composition containing an epoxy resin. The epoxy resin contained in the thermally-conductive epoxy resin molded article has the degree of orientation α equal to or larger than 0.5 and smaller than 1.0. The degree of orientation α is determined by the following equation:

$$\text{degree of orientation } \alpha = (180 - \Delta\beta)/180 \quad \ldots (1)$$

wherein $\Delta\beta$ represents a half-width of a peak in an intensity distribution measured by fixing to a peak scattering angle in an x-ray diffraction measurement, and then changing an azimuth angle from 0 degree to 360 degrees.